

WARPI X FN50H

PARA-GF50

MAIP SRL

Processing/Physical Characteristics	Value	Unit	Test Standard
ISO Data			
Melt flow index, MFI	30	g/10min	ISO 1133
Temperature	275	°C	-
Load	5	kg	-
Molding shrinkage, parallel	0.1	%	ISO 294-4, 2577
Molding shrinkage, normal	0.2	%	ISO 294-4, 2577
Mechanical properties			
ISO Data			
Tensile Modulus	21200	MPa	ISO 527
Stress at break	270	MPa	ISO 527
Strain at break	2	%	ISO 527
Flexural modulus, 23°C	20500	MPa	ISO 178
Flexural strength	400	MPa	ISO 178
Charpy notched impact strength, +23°C	15	kJ/m ²	ISO 179/1eA
Izod impact strength, +23°C	73	kJ/m ²	ISO 180/1U
Izod notched impact strength, +23°C	17	kJ/m ²	ISO 180/1A
Rockwell hardness	R 126	-	ISO 2039-2
Thermal properties			
ISO Data			
Melting temperature, 10°C/min	238	°C	ISO 11357-1/-3
Glass transition temperature, 10°C/min	85	°C	ISO 11357-1/-2
Temp. of deflection under load, 1.80 MPa	230	°C	ISO 75-1/-2
Temp. of deflection under load, 0.45 MPa	235	°C	ISO 75-1/-2
Coeff. of linear therm. expansion, parallel	20	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal	30	E-6/K	ISO 11359-1/-2
Burning behav. at thickness h	HB	class	IEC 60695-11-10
Burning rate, FMVSS, Thickness 1 mm	100	mm/min	ISO 3795 (FMVSS 302)
Glow Wire Flammability Index (GWFI)	750	°C	IEC 60695-2-12
GWFI - thickness tested (1)	3	mm	-
Electrical properties			
ISO Data			
Volume resistivity	1E13	Ohm*m	IEC 62631-3-1
Other properties			
Density	1640	kg/m ³	ISO 1183
Processing Recommendation Injection Molding			
Pre-drying - Temperature	120	°C	-
Pre-drying - Time	2 - 6	h	-
Processing humidity	≤0.08	%	-
Melt temperature	250 - 280	°C	-
Mold temperature	130 - 150	°C	-

Characteristics**Processing**

Injection Molding

Features

Low Warpage

Special Characteristics

Heat stabilized or stable to heat

Regional Availability

Europe